

## SLG46857-AP DIP Adapter

**Abstract**

This document describes the DIP Adapter SLG46857-AP functionality and provides a quick start guide.

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## 1. Terms and Definitions

DIPA	DIP Adapter SLG46857-AP
GPI	General Purpose Input
GPIO	General Purpose Input/Output
IC	Integrated Circuit
SA	Socket Adapter
TP	Test point

## 2. References

- [1] [SLG46857-A](#), Datasheet, Renesas Electronics.

### 3. Introduction and Board Overview

DIPA is a compact, easy-to-use hardware tool that provides SLG46857-AP IC hardware support for design emulation, programming, and real-time testing. DIPA is controlled by Go Configure Hub software with emulation and IC programming.

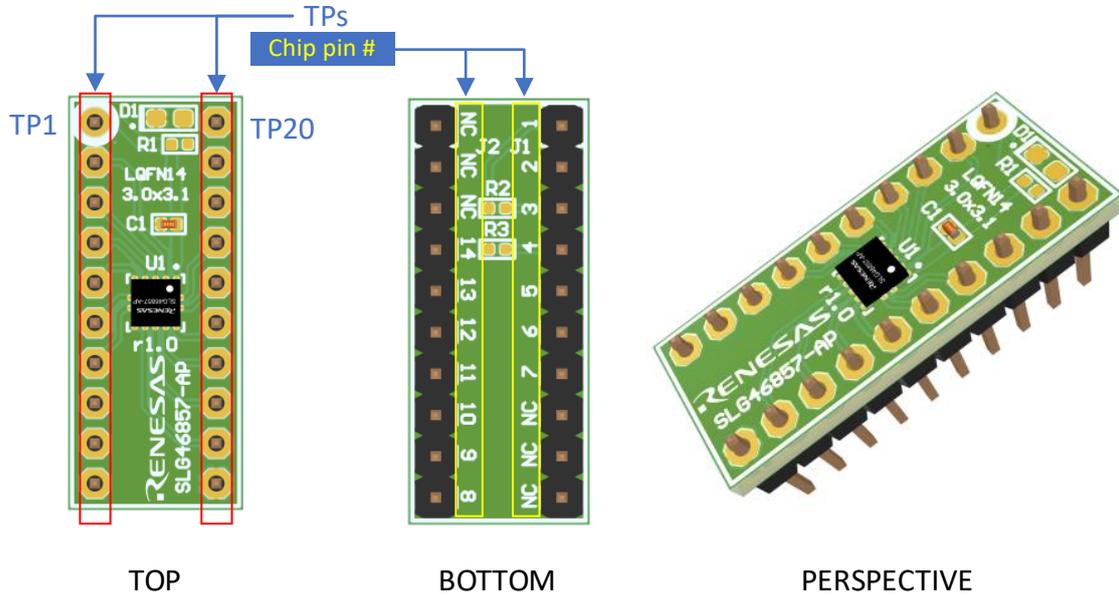


Figure 1. DIPA Views

Table 1. DIPA Pinout Description

Chip pin #	Chip pin name	SA connector J1 pin #	Pin Functions
1	VDD	TP1	Power Supply
2	GPIO	TP2	GPI, SLA_0
3	GPIO0	TP3	GPIO, SCL
4	GPIO1	TP4	GPIO, SDA
5	GPIO2	TP5	GPIO with OE, EXT_Vref0, SLA_1
6	GPIO3	TP6	GPIO with OE
7	GPO0	TP7	GPO, EXT_Vref1
8	GND	TP11	Ground
9	GPIO4	TP12	GPIO with OE, ACMP0_H+, SLA_2
10	GPIO5	TP13	GPIO with OE, ACMP1_H+, SLA_3
11	GPIO6	TP14	GPIO with OE, ACMP2_L+
12	GPIO7	TP15	GPIO with OE, ACMP3_L+
13	GPIO8	TP16	GPIO with OE, Vref0_OUT, TS_OUT
14	GPIO9	TP17	GPIO with OE, Vref1_OUT

## 4. Design Emulation, Programming, and Real-Time Testing

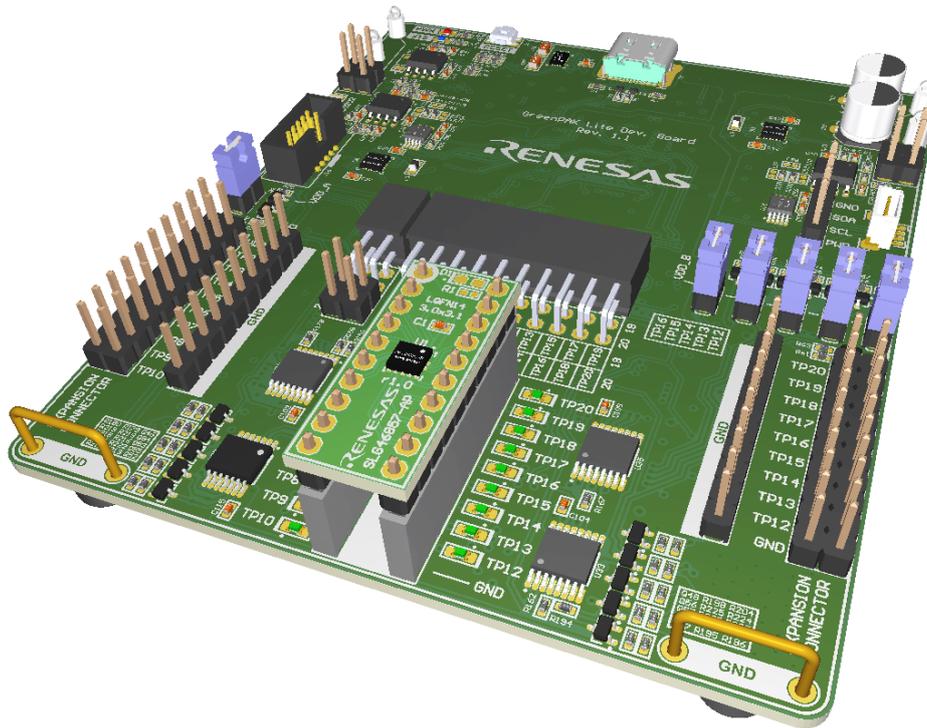


Figure 2. Light Development Board with DIPA

## 5. Board Dimensions

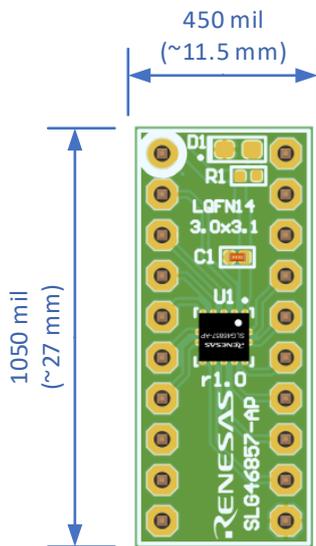


Figure 3. Board Assembly Top View Dimensions

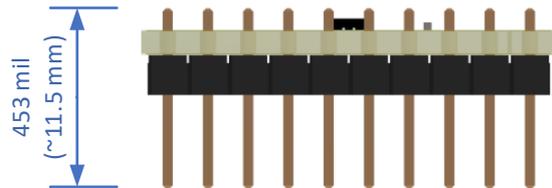


Figure 4. Board Assembly Side View Dimensions

## 6. Schematic Diagrams

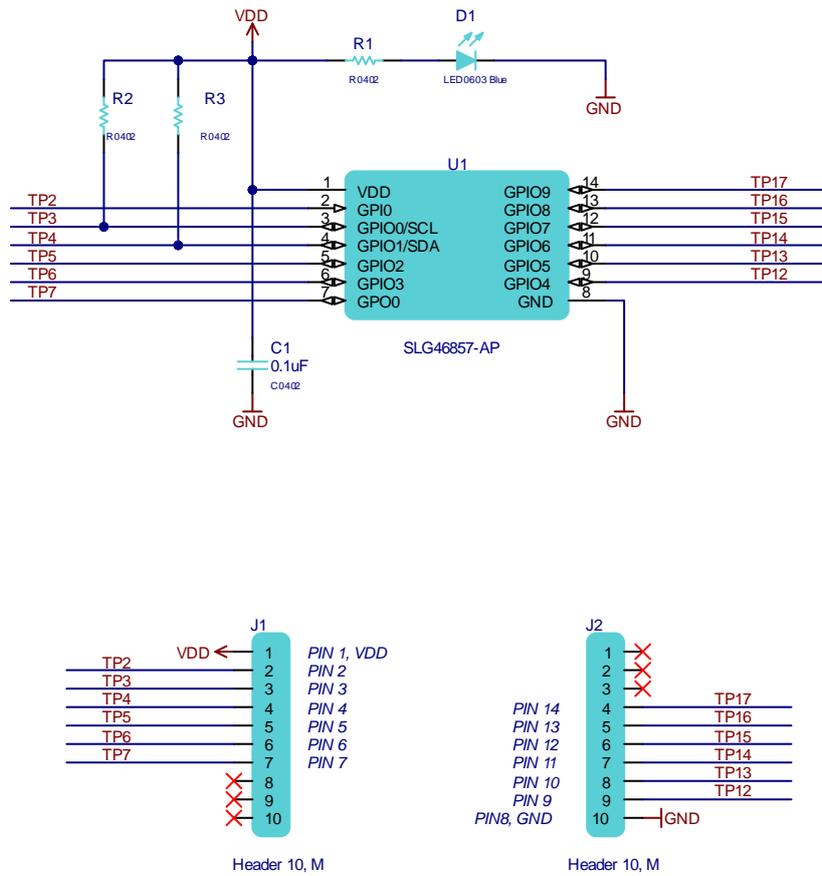


Figure 5. DIPA Board Schematic

**Note:**

D1, R1 are optional (not mounted by default). Can be used for power presence indication.

R2, R3 are optional (not mounted by default). I<sup>2</sup>C pull-ups.

## 7. Bill of Materials

#	Designator	Manufacturer Part Number	Manufacturer 1	Quantity
1	C1	C1005X7R1H104K050BB	TDK	1
2	J1, J2	PH1-10-UA	Adam Equipment	2
3	U1	SLG46857-AP	Renesas Electronics America	1
	Optional			
1	D1	SMD LED 0603	-	1
2	R1	SMD RES 0402 1k	-	1
3	R2, R3	SMD RES 0402 5.1k	-	2

## 8. Revision History

Revision	Date	Description
1.00	Aug 13, 2022	Initial release

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